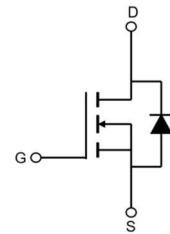
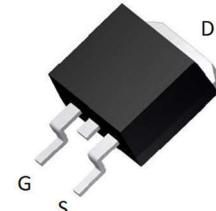


Feature

- 60V,80A
- $R_{DS(on)} < 10m\Omega$ @ $V_{GS}=10V$
- $R_{DS(on)} < 14m\Omega$ @ $V_{GS}=4.5V$
- Advanced Trench Technology
- Lead free product is acquired
- Excellent $R_{DS(on)}$ and Low Gate Charge



Schematic Diagram



TO-263 top view

Application

- PWM applications
- Load Switch
- Power management

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
80N06D	AP80N06D	TO-263	-	-	800

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_a = 25^\circ C$)	I_D	80	A
Continuous Drain Current ($T_a = 100^\circ C$)	I_D	56	A
Pulsed Drain Current ⁽¹⁾	I_{DM}	232	A
Singel Pulsed Avalanche Energy ⁽²⁾	E_{AS}	110	mJ
Power Dissipation	P_D	70	W
Thermal Resistance from Junction to Case	R_{eJC}	2.14	$^\circ C/W$
Junction Temperature	T_J	150	$^\circ C$
Storage Temperature	T_{STG}	-55~+150	$^\circ C$

MOSFET ELECTRICAL CHARACTERISTICS($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = -250\mu\text{A}$	60	-	-	V
Zero gate voltage drain current	I_{DSS}	$V_{\text{DS}} = 60\text{V}, V_{\text{GS}} = 0\text{V}$	-	-	1	μA
Gate-body leakage current	I_{GSS}	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$	-	-	± 100	nA
Gate threshold voltage ⁽³⁾	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$	1	1.7	2.5	V
Drain-source on-resistance ⁽³⁾	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 30\text{A}$	-	7.5	10	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_D = 20\text{A}$	-	10	14	
Forward transconductance ⁽³⁾	g_{FS}	$V_{\text{DS}} = 10\text{V}, I_D = 30\text{A}$	20	-	-	S
Dynamic characteristics						
Input Capacitance	C_{iss}	$V_{\text{DS}} = 25\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	4400	-	pF
Output Capacitance	C_{oss}		-	210	-	
Reverse Transfer Capacitance	C_{rss}		-	190	-	
Switching characteristics						
Turn-on delay time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 30\text{V}, I_D = 30\text{A}, R_L = 1\Omega$ $V_{\text{GS}} = 10\text{V}, R_G = 3\Omega$	-	7.1	-	ns
Turn-on rise time	t_r		-	5.3	-	
Turn-off delay time	$t_{\text{d}(\text{off})}$		-	27.2	-	
Turn-off fall time	t_f		-	6.2	-	
Total Gate Charge	Q_g	$V_{\text{DS}} = 30\text{V}, I_D = 30\text{A},$ $V_{\text{GS}} = 10\text{V}$	-	77	-	nC
Gate-Source Charge	Q_{gs}		-	9	-	
Gate-Drain Charge	Q_{gd}		-	23	-	
Source-Drain Diode characteristics						
Diode Forward voltage ⁽³⁾	V_{DS}	$V_{\text{GS}} = 0\text{V}, I_S = 30\text{A}$	-	-	1.2	V
Diode Forward current ⁽⁴⁾	I_S		-	-	80	A
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, I_F = 30\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		29		ns
Body Diode Reverse Recovery Charge	Q_{rr}	$T_J = 25^\circ\text{C}, I_F = 30\text{A}, dI/dt = 100\text{A}/\mu\text{s}$		45		nc

Notes:

1. Repetitive Rating: pulse width limited by maximum junction temperature
2. EAS Condition: $T_J = 25^\circ\text{C}, V_{\text{DD}} = 20\text{V}, R_G = 25\Omega, L = 0.5\text{mH}, I_{\text{AS}} = 21\text{A}$
3. Pulse Test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
4. Surface Mounted on FR4 Board, $t \leq 10$ sec

Test Circuit

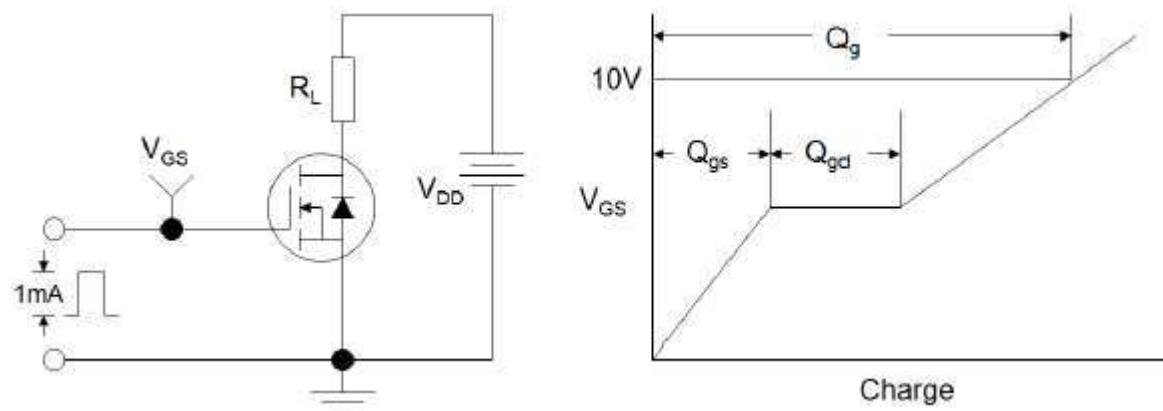


Figure1:Gate Charge Test Circuit & Waveform

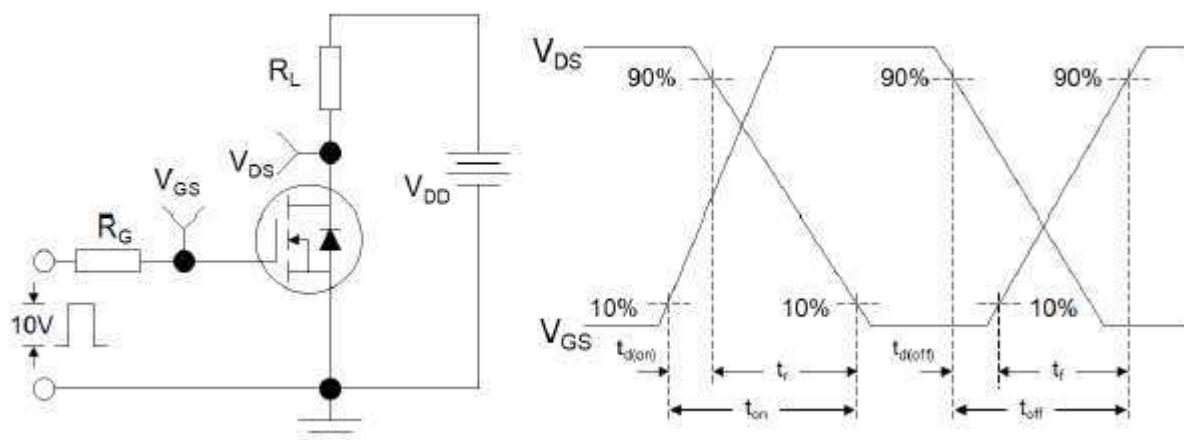


Figure 2: Resistive Switching Test Circuit & Waveforms

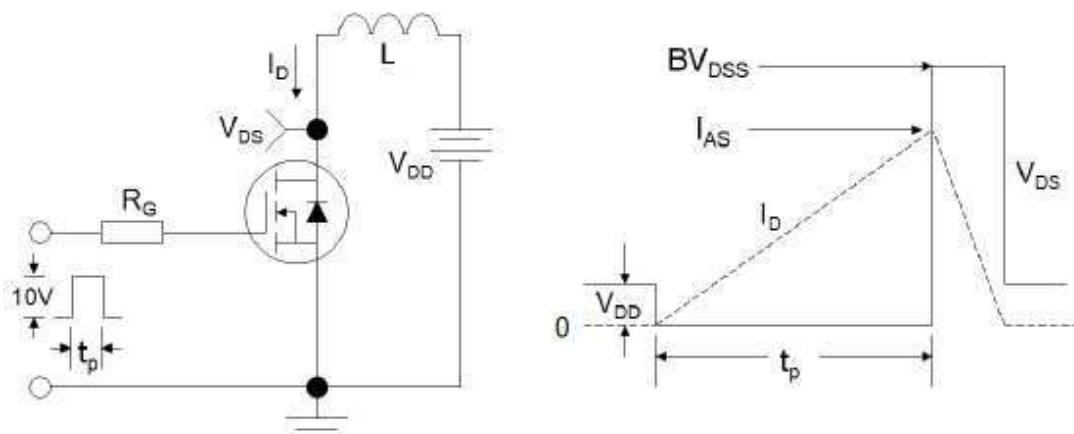


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

Figure 1: Output Characteristics

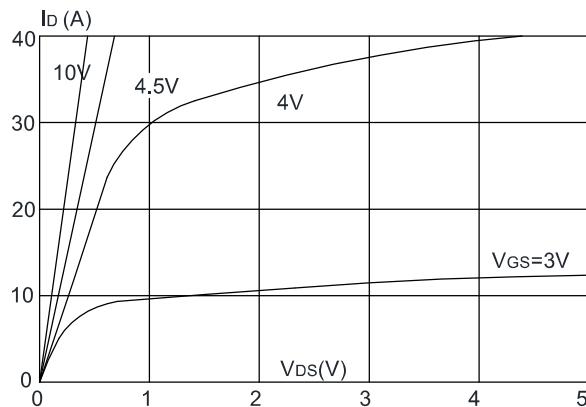


Figure 3: On-resistance vs. Drain Current

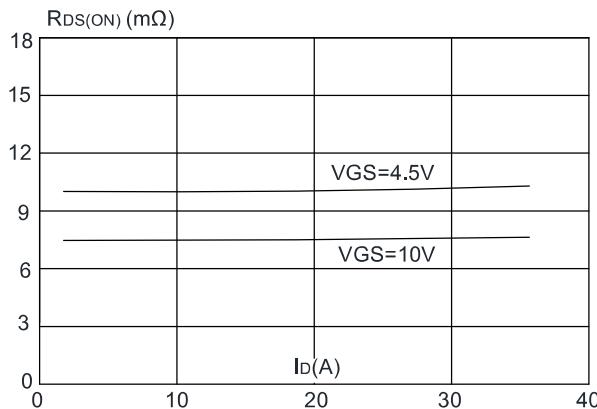


Figure 5: Gate Charge Characteristics

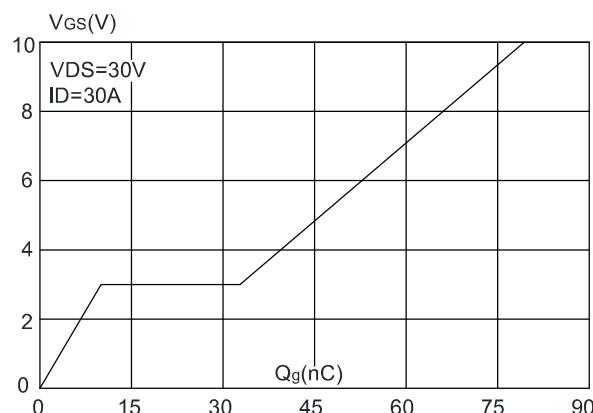


Figure 2: Typical Transfer Characteristics

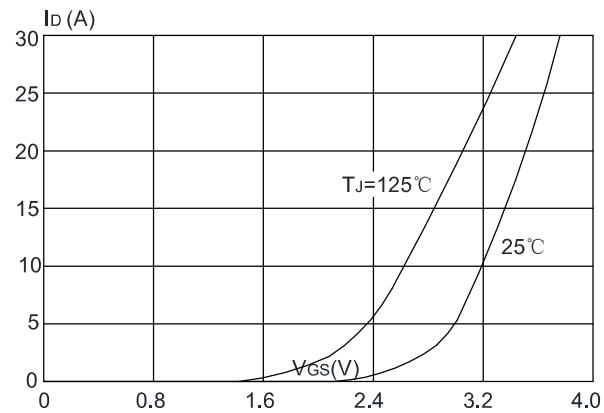


Figure 4: Body Diode Characteristics

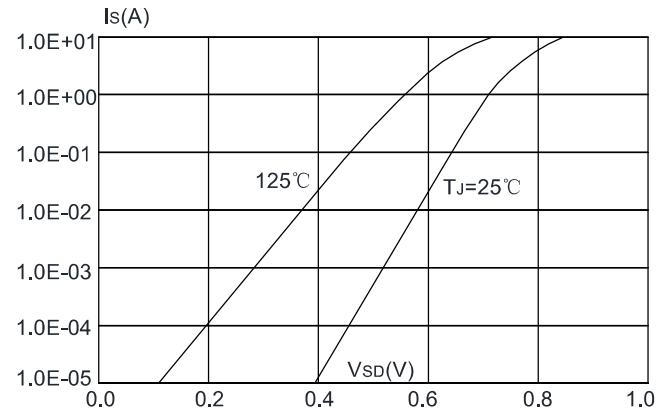


Figure 6: Capacitance Characteristics

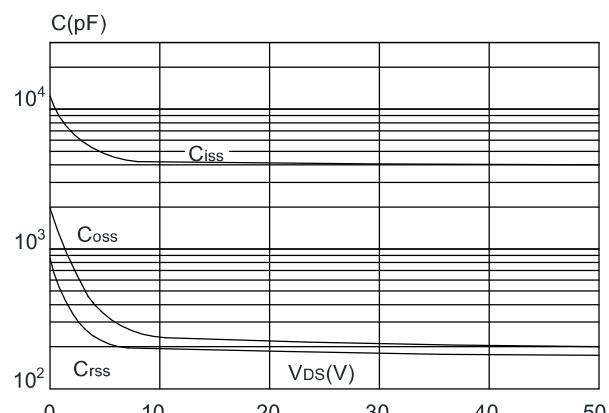


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

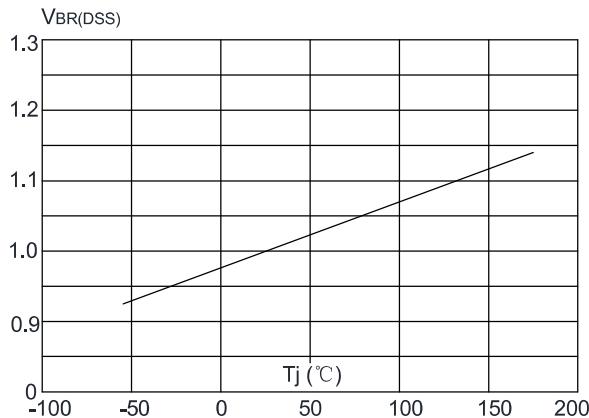


Figure 8: Normalized on Resistance vs. Junction Temperature

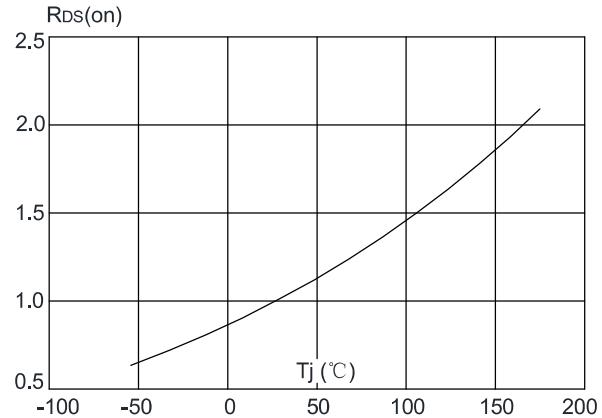


Figure 9: Maximum Safe Operating Area

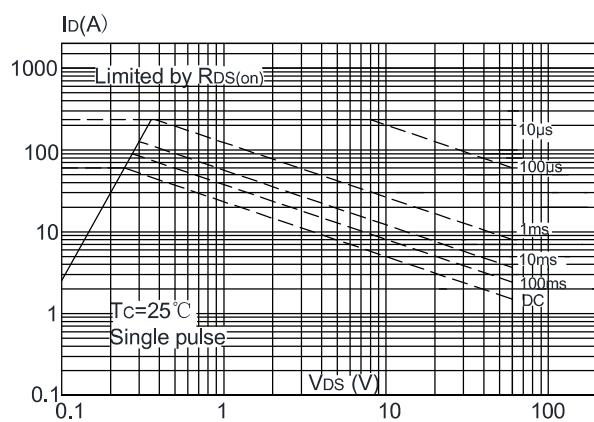


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

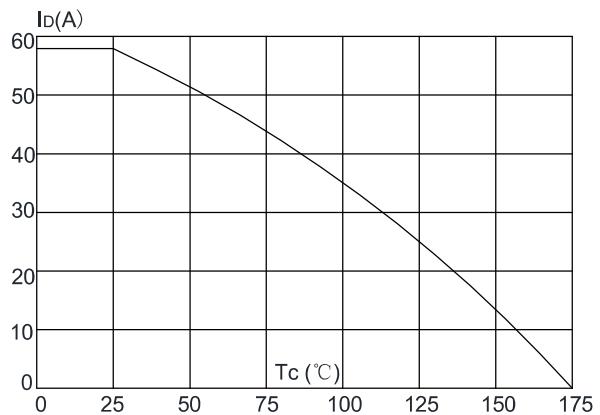
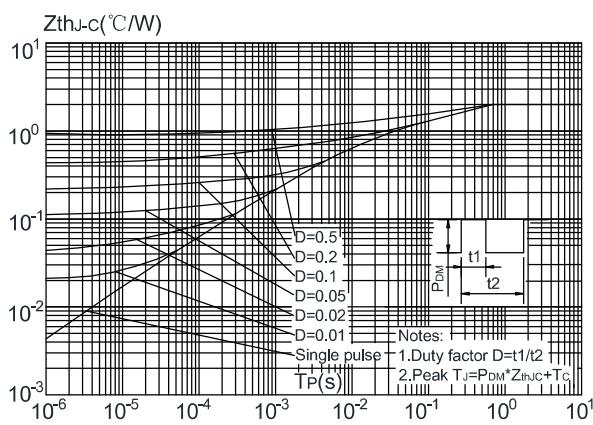
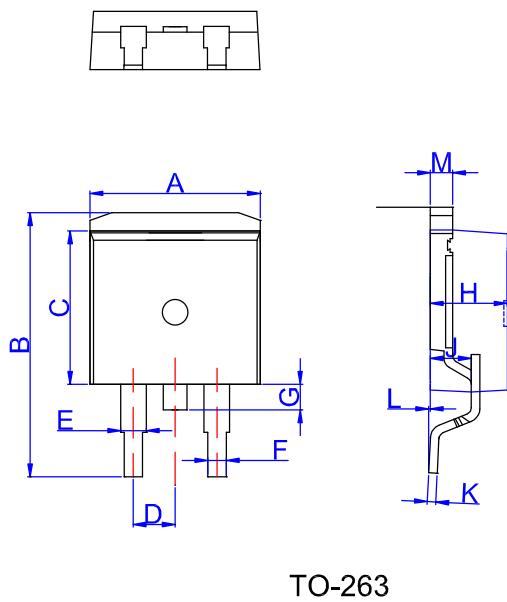


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



TO-263 Package Information



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	9.90		10.20	0.390		0.402
B	14.70		15.80	0.579		0.622
C	9.4		9.6	0.37		0.378
D		2.54			0.100	
E	1.20		1.40	0.047		0.055
F	0.75		0.85	0.029		0.033
G			1.75			0.069
H	4.40		4.70	0.173		0.185
J	2.30		2.70	0.091		0.106
K	0.38		0.55	0.015		0.022
L	0	0.10	0.25	0	0.004	0.010
M	1.25		1.35	0.049		0.053